



## Material Composition Sheet

Product: GS9001-CTM  
 Package Type: MQFP-44 250/reelTaped  
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		32.19	Al	0.19	0.59	5902
			Si	32.00	99.40	994098
			Sub-total:	32.19	99.99	1000000
Die Attach		4.87	Epoxy Resin	1.22	25.05	250513
			Silver	3.65	74.94	749487
			Sub-total:	4.87	99.99	1000000
Lead Finish External		6.79	Pb	1.69	24.88	248895
			Sn	5.10	75.11	751105
			Sub-total:	6.79	99.99	1000000
Lead Finish Internal Leadframe		120.78	Cu	116.95	96.82	968289
			Mg	0.18	0.14	1490
			Ni	3.65	3.02	30220
			Sub-total:	120.78	99.98	999999
Marking Ink		0.01		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound		337.74	Br	2.02	0.59	5981
			Epoxy Resin	60.15	17.80	178096
			Sb	4.88	1.44	14449
			SiO2	270.69	80.14	801475
			Sub-total:	337.74	99.97	1000001
Wires		2.62	Au	2.62	100.00	1000000
			Sub-total:	2.62	100.00	1000000
<b>Total:</b>		<b>505.00</b>				

### GENNUM CORPORATION

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